DESOLDERING BRAIDS

M.G. Chemicals desoldering braids (wicks) are made of clean, oxide-free copper wire, tight-weaved. They are specially designed to ease the replacement of electronics components and remove any extra solder without damaging the board or components. They are ideal for the reworking and repair of printed circuit boards found in a variety of electronics devices. Our desoldering braids are available in Type 'R', Lead-Free or No Clean formats, and are offered in a wide variety of lengths and widths. Static dissipative wicks come in 5-foot spools and can be custom-ordered in any other size. Packs are also available.

Fine Braid Super Wick 400 - LF Series

M.G. Chemicals Lead Free Super Wick LF Series are formulated to remove high-temperature lead-free solders. All are formulated with a no-clean flux designed for higher activation temperatures. They also work well with conventional tin/lead solders. They transfer heat to solder joints more quickly and efficiently than conventional wicks.

- **For lead-free solder**
- **No-clean flux**
- **Transfer heat rapidly**
- **Static dissipative bobbins**
- **Meet J-STD-004 requirements**
- **Conform to Bellcore specification GR-78-CORE (TR-TSY-000078), and IPC Test Method III**

Length	0.05" # 2 Yellow	0.075" #3 Green	0.1" #3 Blue
5 ft	424-LF	425-LF	426-LF

Fine Braid Super Wick 400 - NS Series

M.G. Chemicals Super Wick NS Series braids are high quality desoldering braids made from high-purity oxide-free copper and formulated for the removal of leaded solders. A no-clean flux provides higher temperature activation. Can also be used with lead-free solder chemistry. Its faster heat transfer properties allow for safer and quicker solder removal.

- **No Clean Super Wick**
- **Flux residue is non-conductive and non-corrosive**
- **ESD (electrostatic dissipative) safe for all 1.5 m / 5 ft bobbins**
- **Flux residue remaining on board does not have to be cleaned**
- **High SIR-meets the requirements of both the Bellcore Spec. TR-TSY-000078 and IPC Test Method III**

Length	0.05" #2 Yellow	0.075" #3 Green	0.1" #4 Blue
5 ft	424-NS	425-NS	426-NS
50 ft	-	453-NS	454-NS
5 ft - 10 pack	424-NS-10	425-NS-10	426-NS-10

Fine Braid Super Wick 400 Series

MG 4xx series Super Wick Fine Braids are high quality desoldering braids that have been precision cleaned and produced with up-to-date and environmentally friendly processes and technology. The oxide-free high purity copper conducts heat fast, allowing for faster wicking and shorter dwell times that minimize possible overheating damage. They use pure type 'R' resin flux that conforms to all the requirements of MIL-F-14256F, Type 'R' and ANSI/J-STD-004. They leave an environmentally safe residue. In short, they are cleaner, faster and more consistent desoldering braids.

- **Reactive flux core (R)**
- **High purity, oxide-free copper**
- **Works with leaded or lead-free chemistries**
- **Environmentally and PCB safe residues**
- **ESD (electrostatic dissipative) safe for 1.5 m [5 ft]**
- **Manufactured under SPC guidelines**
- **Conforms to MIL-F-14256F**
- **ANSI/J-STD-004 compliant**

Length	0.025" #1 White	0.05" #2 Yellow	0.075" #3 Green	0.1" #4 Blue	0.125" #5 Brown
5 ft	423	424	425	426	427
25 ft		442	443	444	
50 ft		452	453	454	
100 ft		462	463	464	
5 ft - 10 pack		424-10	425-10	426-10	427-10

INDUSTRY STANDARDS AND REQUIREMENTS

The electronics industry has set three joint standards that prescribe the requirements and test methods for soldering materials used in their work. These standards are J-STD-004, J-STD-005 and J-STD-006.

J-STD-004B

The J-STD-004B standard prescribes general requirements for the classification and characterization of fluxes for high quality solder interconnections. It is used for quality control and procurement purposes.

This standard classifies and characterizes tin/lead and lead-free soldering flux materials for use in electronic metallurgical interconnections for printed circuit board assembly. Soldering flux materials include liquid flux, paste flux, solder paste, solder cream, flux-coated and flux-cored solder wires, and preforms. This standard is not intended to exclude any acceptable flux or soldering materials; however, such materials must produce the desired electrical and metallurgical interconnections.

J-STD-005

The J-STD-005 standard prescribes general requirements for the characterization and testing of solder pastes used to make high quality electronics interconnections. This specification is a material quality control document and is not intended to relate directly to the material's performance in the assembly process. Solder paste users are referred to 6.3 for a listing of requirements information, and options that should be addressed when procuring solder paste.

The standard defines the characteristics of solder paste through the definition of properties, and the specification of test methods and inspection criteria. Materials involved include solder powders and solder paste flux blended to produce solder paste. Solder powders are classified by the shape and distribution of their constituent particles. This standard is not intended to exclude particle sizes or distributions not specifically listed.

J-STD-006C

The J-STD-006C standard prescribes the nomenclature, requirements and test methods used for electronics-grade solder alloys; for fluxed and non-fluxed bar, ribbon, wire, and powder solders for electronic soldering applications; and for "special form" electronics-grade solders. This is a quality control standard and is not intended to relate directly to the materials' performances in the manufacturing process.

RoHS

RoHS (Restriction of Hazardous Substance, also known as Directive 2002/95/EC) originated in the European Union and restricts the use of six hazardous materials found in electrical and electronics products. All applicable products in the EU market after July 1, 2006 must meet RoHS compliance standards. RoHS impacts the entire electronics industry.

The substances restricted under the RoHS directive include lead (Pb), mercury (Hg), cadmium (Cd), hexavalent chromium (CrVI), polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE).

Any business that sells applicable electrical or electronics products, sub-assemblies or components directly to RoHS countries, or sells to resellers, distributors or integrators that in turn sell products to these countries, is affected if they utilize any of the restricted materials.

With the exception of our leaded solder wires, MG Chemicals does not produce any products containing any of the six substances controlled by RoHS.

For more information on the above regulatory issues, please visit the Compliance Center on our website.

CONFLICT MINERALS

MG Chemicals Ltd. supports the elimination of conflict resources trade in accordance with the Dodd-Frank Financial Reform Bill. Our policy is to use only materials that haven't financed or benefited DRC armed groups, and are therefore either "DRC Conflict Free" or made from recycled materials. Our suppliers are made directly aware of this requirement and are asked to trace the source of their products back to their original smelters or refineries. Further, our suppliers are asked to report changes to their conflict minerals sourcing that would impact their DRC Conflict Free status.